

INTERCONNECTS

SERIES 850, 851, 852, 853 • .050" GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

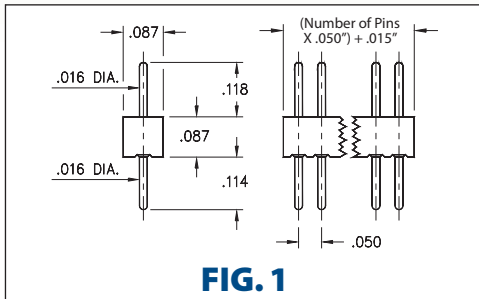


FIG. 1



FIG. 2

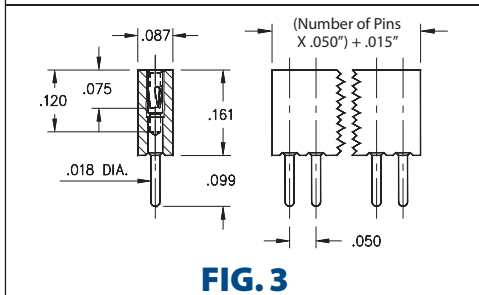


FIG. 3

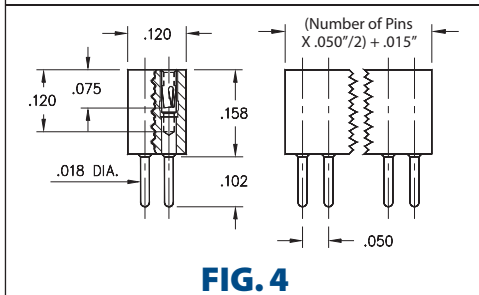


FIG. 4

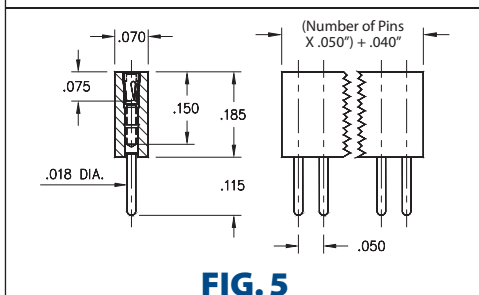
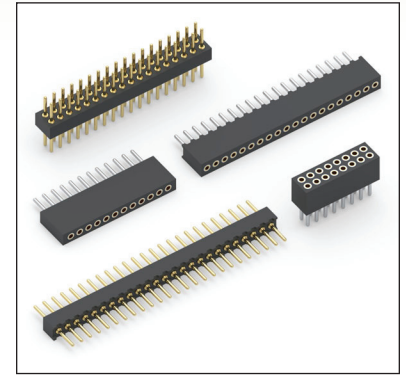


FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248"
- Pin headers have .016" dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from .015"-.020"). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001 Single Row .087" Profile Pin Header				
	850-XX-0__-10-001000 Specify number of pins 01-50				
FIG. 2	Series 852...001 Double Row .083" Profile Pin Header				
	852-XX-__-10-001000 Specify number of pins 004-100				
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264					
SPECIFY PLATING CODE XX=		10	90	40	
Pin Plating		10 μ" Au	200 μ" Sn/Pb	200 μ" Sn	

FIG. 3	Series 851...001 Single Row .161" Profile Socket							
	851-XX-0__-10-001000 Specify number of pins 01-50							
FIG. 4	Series 853...001 Double Row .161" Profile Socket							
	853-XX-__-10-001000 Specify number of pins 004-100							
FIG. 5	Series 851...002 Single Row .185" Profile Socket							
	851-XX-0__-10-002000 Specify number of pins 01-77							
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264								
SPECIFY PLATING CODE XX=			91	93	99	41	43	47
Sleeve (Pin)			200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn	200 μ" Sn	200 μ" Sn
Contact (Clip)			10 μ" Au	30 μ" Au	100 μ" Sn/Pb	10 μ" Au	30 μ" Au	Au Flash

